PCN Number:		20140227000						PCN Date: 02/28/2014				
Title: Green Mold C			ompound Conversion for LMP7704MT(X)/NOPB									
Customer Contact:		PCN Manager		nager	Phone:	+1(214)480-6037			Dept:	ept: Quality		
Proposed 1 st Ship Da				6/01/2014	Estim	ated Sam	ated Sample Avail		bility:	Services 03/01/2014		
Change Type:				0,01,2011	Lotin				Billeyi	05/0	51/2011	
Assembly Site			Assembly Process Asse				embly Materials					
Design				Electrical Specification					echanical Specification			
Test Site				Packing/Shipping/Labeling				Test	est Process			
Wafer Bump Site				Wafer Bump Material					er Bump			
Wafe	er Fab Site				Wafer Fab Materials			Wafer Fab Process				
				Part number								
_					PCN De	etails						
Descript	ion of Chang	e:										
	704MT(X)/NC						o gre	en mo	old comp	ounc	1. No other	
	Mold Com	pou	nd		80644				4209002	2		
Reason for Change: ROHS compliancy. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): None Changes to product identification resulting from this PCN:												
Sample product shipping label - Matte Sn Finish (not actual product label) TEXAS INSTRUMENTS MADE IN: Malaysia 20: 20: 20: 20: 20: 20: 20: 20:												

Qualification Data: Approved November, 2009

Qual Vehicle: LMP2234AMTX/NOPB (MSL1-260C)						
Package Construction Details						
Assembly Site	TIEM Mold		Compound:	4209002		
# Pins-Designator, Family	: 14-PW, TSSOP	Mount Compound:		8080598		
Lead Finish	Matte Sn	Bond Wi		Au, 1.0 mil		
Qualification: 🗌 Plan 🛛 Test Results						
Reliability Test	Conditions		Sample Size/Fail			
Reliability Test			Lot#1	Lot#2		
SOPL 1	125C (1000 Hrs)		77/0	77/0		
**Autoclave 121C 1	21C, 2 atm (96 Hrs)	45/0	45/0			
**T/C -65C/150C -	55C/+150C (1000 Cyc)		77/0	70/0		
** - Test requires Moisture Preconditioning (MSL1-260C)						

Reference Qualification Data: Approved May, 2007 This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: LMB4008M1-6/NOPB (MSL 2A-260C)						
Package Construction Details						
Assembly Site:	TIEM Mol		d Compo	ound:	4209002	
# Pins-Designator, Family:	DW-20, SOIC	Moun	Mount Compound:		8080598	
Lead Finish:	Matte Sn	Bond Wire:		Wire:	Au, 1.0 mil	
Qualification: 🗌 Plan 🛛 Test Results						
Reliability Test	Conditions		Sample Size / Fail			
Reliability rest			Lot 1	Lot 2	Lot 3	
SOPL 1	150C (1000 Hrs)		77/0	77/0	77/0	
**Autoclave 121C	121C, 2 atm (96 Hrs)		77/0	77/0	77/0	
**THBT 8	85C/85%RH (96 Hrs)		77/0	77/0	77/0	
**T/C -65C/150C -	65C/+150C (1000 Cyc)		77/0	77/0	77/0	
Notes: **Tests require preconditioning sequence: MSL2A-260C						

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com